

ウェハレベル接合を用いたコンデンサ
マイクロフォン by K.C. Lee et al.

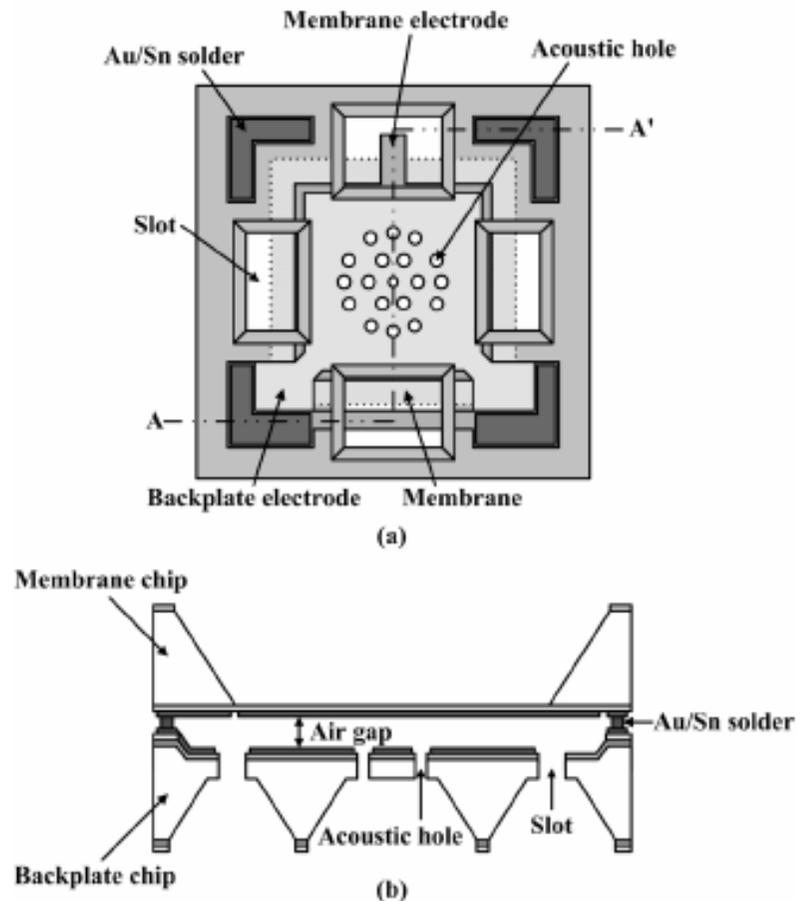


Figure 1: (a) Top view and (b) cross-sectional view along the line A-A' of the proposed condenser microphone.

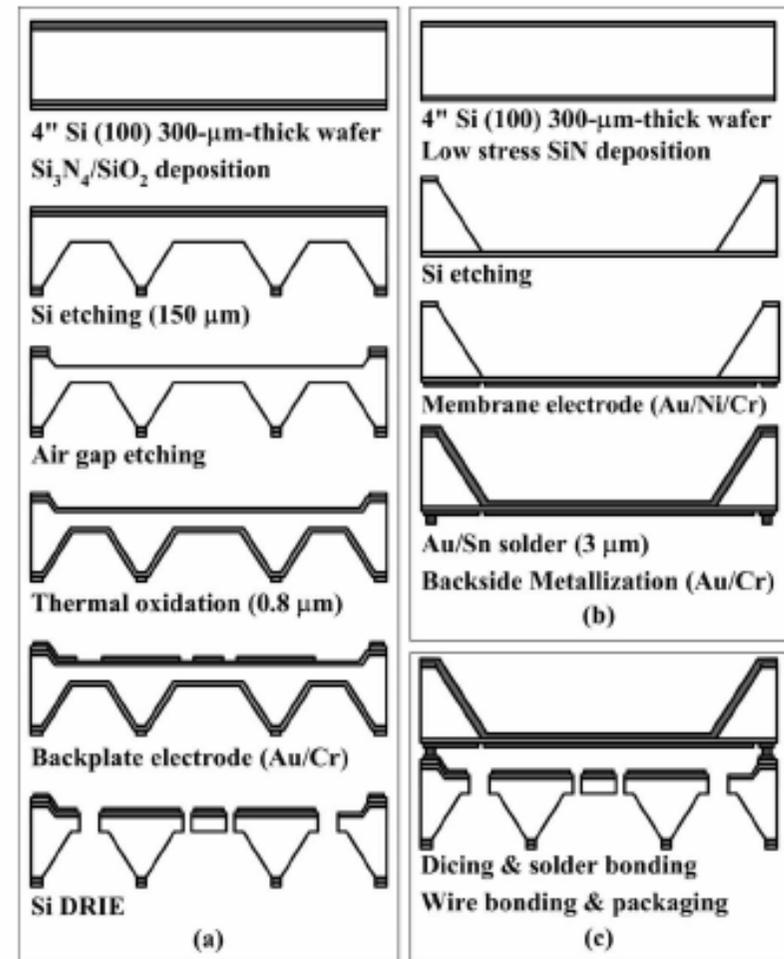


Figure 2: Fabrication processes of the condenser microphone: (a) backplate wafer, (b) membrane wafer, and (c) bonding and packaging processes.

バックプレートウェハとメンブレンウェハは、Au / Sn共晶点接合を使って、一体化される。